

CHANGE NOTIFICATION



Linear Technology Corporation
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(408) 432-1900

April 25, 2013

Dear Sir/Madam:

PCN# 042513

Subject: Notification of Assembly Process change for LTM8029 and LTM8032

Please be advised that Linear Technology Corporation has made a minor change to the internal package construction to facilitate the use of one attach material for both die and components. The die attach material is changed from epoxy to solder, which is already used for attaching components in the same μ Module device package. In order to use the solder die attach, the die attach paddle (DAP) has been modified by splitting the DAP into multiple pads for dice D1 and U1. Linear has been shipping several μ Module devices using solder for die attach and component attach.

Besides these changes, no functional, parametric, mechanical, or datasheet specifications are affected and the component bill of materials remains unchanged. Similarly, there are no changes associated with the package footprint, PCB layout or product top marking, so the customer applications will be unaffected.

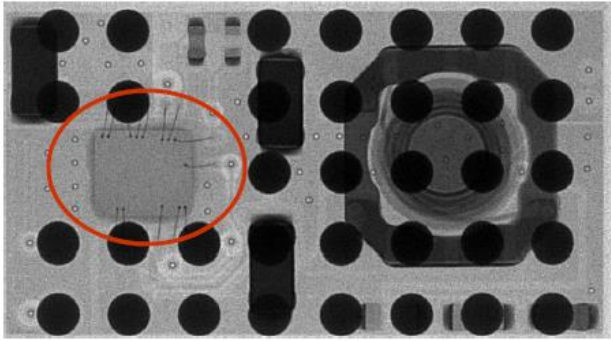
Parts incorporating the new substrate design have been fully characterized and tested for package level reliability. The change was qualified by performing extensive characterization over the full operating voltage and temperature ranges and MSL3 preconditioning. Devices from the same μ Module device product families have been subjected to 1000 cycles of temperature cycles and thermal shock. Products built using the improved design are targeted for shipment around late July 2013.

Should you have any further questions, please feel free to contact me at 408-432-1900 ext. 2519, or by E-mail at NGIRN@linear.com. If I do not hear from you by May 26th, 2013, we will consider this change approved by your company.

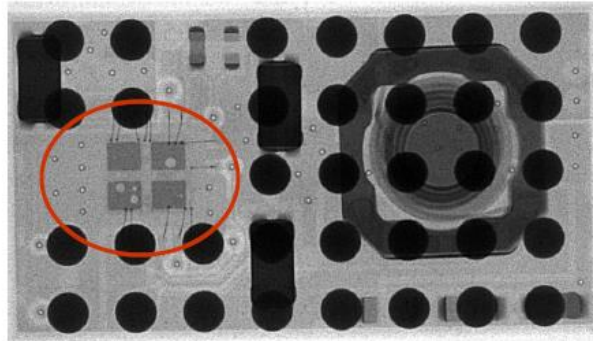
Sincerely,

Naib Girm
Quality Assurance Manage

LTM8029- Current and New DESIGN

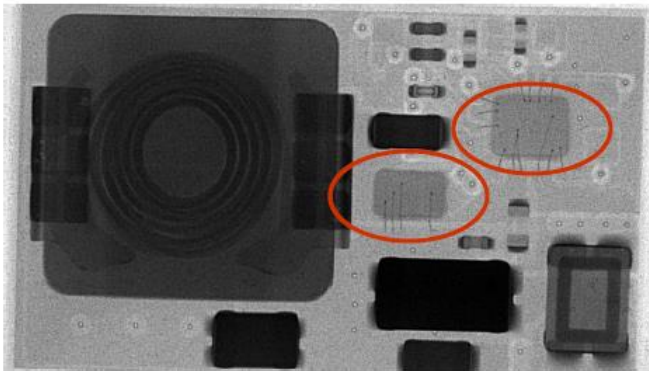


Current Design

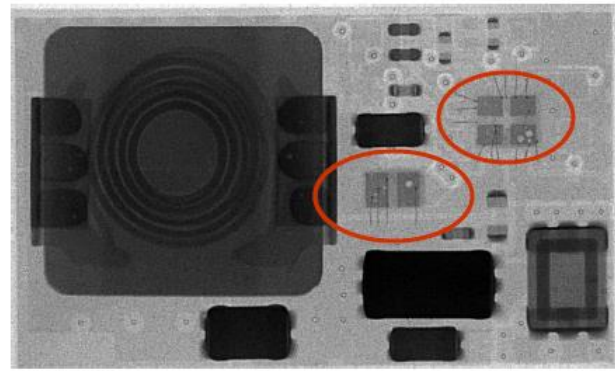


New Design

LTM8032 Current and New Design



Current Design



New Design

PACKAGE RELIABILITY DATA
LTM80xx Solder Die Attach Qualification Report

4/17/2013

• OPERATING LIFE TEST

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS AT +150°C	NUMBER OF FAILURES
LTM8008	77	1210	1210	77.00	0
	77			77.00	0

• J-STD-020 MSL 3 PRECONDITIONING: 192h +30°C/60%R.H. SOAK, 3x REFLOW AT +245°C PEAK

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE		NUMBER OF FAILURES
LTM8001	199	1236	1236		0
LTM8008	462	1210	1210		0
LTM8023	204	1245	1245		0
LTM8025	204	1245	1245		0
LTM8028	184	1236	1236		0
LTM8029	246	1239	1239		0
LTM8032	204	1302	1302		0
LTM8045	152	1225	1225		0
LTM8047	77	1242	1242		0
LTM8048	274	1232	1236		0
LTM8052	358	1239	1239		0
LTM8058	204	1239	1239		0
	2,768				0

• HIGH TEMPERATURE BAKE at 150°C

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS AT +150°C	NUMBER OF FAILURES
LTM8001	25	1236	1236	25.00	0
LTM8008	77	1210	1210	77.00	0
LTM8023	50	1245	1245	50.00	0
LTM8025	50	1245	1245	50.00	0
LTM8029	50	1239	1239	50.00	0
LTM8045	50	1225	1225	50.00	0
LTM8052	50	1239	1239	50.00	0
LTM8058	50	1239	1239	50.00	0
	402			402.00	0

• HIGHLY ACCELERATED STRESS TEST (+131°C/85%R.H. w BIAS)

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS AT +85°C	NUMBER OF FAILURES
LTM8008	46	1210	1210	88.32	0
	46			88.32	0

• UNBIASED HIGHLY ACCELERATED STRESS TEST (+131°C/85%R.H.) ⁽¹⁾

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS AT +131°C	NUMBER OF FAILURES
LTM8001	43	1236	1236	4.13	0
LTM8023	50	1245	1245	4.80	0
LTM8025	50	1245	1245	4.80	0
LTM8028	30	1236	1236	2.88	0
LTM8029	70	1239	1239	6.72	0
LTM8045	49	1225	1225	8.23	0
LTM8048	46	1236	1236	2.21	0
LTM8052	50	1239	1239	4.80	0
LTM8058	50	1239	1239	4.80	0
	438			43.37	0

PACKAGE RELIABILITY DATA
LTM80xx Solder Die Attach Qualification Report

4/17/2013

• TEMPERATURE/HUMIDITY STORAGE (+85°C/85%R.H.) ⁽¹⁾

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS AT +85°C	NUMBER OF FAILURES
LTM8008	77	1210	1210	77.00	0
	77			77.00	0

• TEMP CYCLE FROM -65°C to +150°C ⁽¹⁾

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
LTM8008	231	1210	1210	231.00	0
LTM8052	77	1239	1239	38.50	0
	308			269.50	0

• TEMP CYCLE FROM -55°C to +125°C ⁽¹⁾

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
LTM8001	77	1236	1236	77.00	0
LTM8023	77	1245	1245	77.00	0
LTM8025	77	1245	1245	77.00	0
LTM8028	77	1236	1236	77.00	0
LTM8029	77	1239	1239	77.00	0
LTM8045	77	1225	1225	77.00	0
LTM8047	77	1242	1242	77.00	0
LTM8048	102	1232	1236	140.50	0
LTM8052	77	1239	1239	77.00	0
LTM8058	77	1239	1239	77.00	0
	795			833.50	0

• THERMAL SHOCK FROM -65°C to +150°C ⁽¹⁾

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
LTM8008	231	1210	1210	231.00	0
LTM8052	77	1239	1239	77.00	0
	308			308.00	0

• THERMAL SHOCK FROM -55°C to +125°C ⁽¹⁾

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
LTM8001	77	1236	1236	77.00	0
LTM8023	77	1245	1245	77.00	0
LTM8025	77	1245	1245	77.00	0
LTM8028	77	1236	1236	77.00	0
LTM8029	77	1239	1239	77.00	0
LTM8045	75	1225	1225	75.00	0
LTM8048	126	1232	1236	126.00	0
LTM8052	77	1239	1239	77.00	0
LTM8058	77	1239	1239	77.00	0
	740			740.00	0

• BOARD MOUNT TEMP CYCLE FROM -40°C to +125°C

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
LTM8008	15	1210	1210	22.50	0
	15			22.50	0

(1) Environmental stress are preceded by JEDEC Level 3 Preconditioning: 192h 30°C/80% R.H. soak, followed by 3x Reflow at 245°C